

**date** 03/29/2017

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SERIES: HSS-B20-02 | DESCRIPTION: HEAT SINK

#### **FEATURES**

- TO-220 package
- available with and without solder pins
- folded backfins for maximum cooling
- black anodized finish





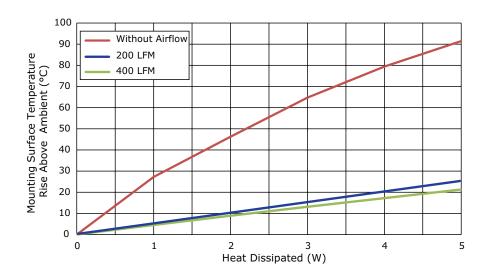
MODEL	solder pin		thermal resistance <sup>1</sup>				power dissipation <sup>1</sup>
	orientation	length (mm)	<pre>@ 75°C △T,     nat conv     (°C/W)</pre>	<pre>@ 1 W, nat conv (°C/W)</pre>	@ 1 W, 200 LFM (°C/W)	@ 1 W, 400 LFM (°C/W)	@ 75°C ΔT, nat conv (W)
HSS-B20-074H	horizontal	7.4	20.59	27.22	5.39	4.51	3.64
HSS-B20-097H	horizontal	9.7	20.59	27.22	5.39	4.51	3.64
HSS-B20-NP-02	no pin		20.59	27.22	5.39	4.51	3.64

Note: 1. See performance curves for full thermal resistance details.

## **PERFORMANCE CURVES**

	Heatsink Temperature Rise Above Ambient ( $\Delta T = Ths - Ta$ ) (°C)				
Power (W)	Natural Conv.	200 LFM	400 LFM		
0	0	0	0		
1	27.22	5.39	4.51		
2	46.27	10.41	8.92		
3	64.76	15.66	13.12		
4	79.42	20.53	17.21		
5	91.49	25.37	21.27		

Ths: "hot spot" temperature measured on the heatsink Ta: ambient temperature



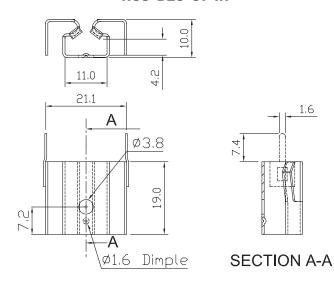
# **MECHANICAL DRAWING**

units: mm

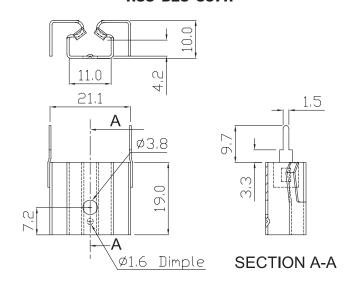
tolerance: ±0.5 mm

MATERIAL	AL5052	
FINISH	black anodized	
THICKNESS	0.8 mm	
PIN MATERIAL	brass	
PIN PLATING	tin	
WEIGHT	HSS-B20-074H: 3.0 g HSS-B20-097H: 3.0 g HSS-B20-NP-02: 2.6 g	

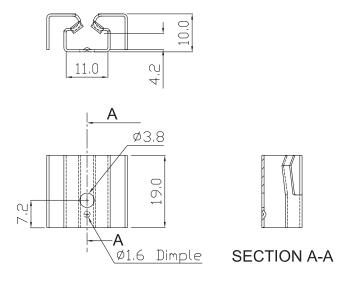
#### HSS-B20-074H



## HSS-B20-097H



#### HSS-B20-NP-02



CUI Inc | SERIES: HSS-B20-02 | DESCRIPTION: HEAT SINK

### **REVISION HISTORY**

rev.	description	date
1.0	initial release	03/29/2017

The revision history provided is for informational purposes only and is believed to be accurate.



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CUI offers a one (1) year limited warranty. Complete warranty information is listed on our website.

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